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PART OBSOLETE - USE PI3PCIE3412A

A product Line of
Diodes Incorporated

PI3PCIE3412

3.3V, PCI Express® 3.0 2-Lane, 2:1 Mux/DeMux Switch, with Single Enable

Features

- 4 Differential Channel, 2:1 Mux/DeMux
- PCI Express® 3.0 Performance, 8.0Gbps
- Bi-directional Operation
- Low Bit-to-Bit Skew, 10ps max
- Low channel-to-channel skew, 20ps max
- Low Crosstalk: -35dB@4 GHz
- High Off Isolation: -22dB@4 GHz (8.0Gbps)
- Low insertion loss: -1.3dB@4 GHz (8.0Gbps)
- Return loss: -21dB@4 GHz
- Support for DP1.2 - HBR2, HBR, RBR
- Supply Voltage 3.3V
- Industrial Temperature Range: -40°C to 85°C
- Packaging (Pb-free & Green):
  - 42-contact, TQFN (ZH42), 3.5 x 9mm
  - 40-contact, TQFN (ZL40), 3 x 6mm

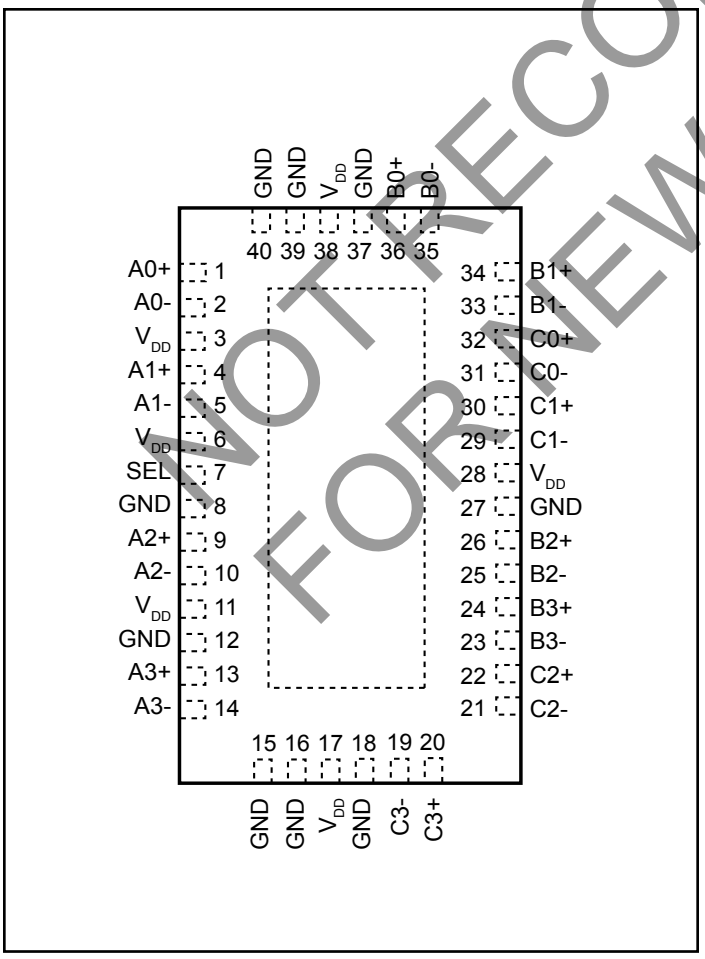
Description

The PI3PCIE3412 is an 8 to 4 differential channel multiplexer/ demultiplexer switch. This solution can switch 2 full PCI Express® 3.0, lanes to one of two locations. Using a unique design technique, Diodes has been able to minimize the impedance of the switch such that the attenuation observed through the switch is minimal. The unique design technique also offers a layout targeted for PCI Express signals, which minimizes the channel to channel skew as well as channel to channel crosstalk as required by the PCI Express specification. PI3PCIE3412 can also be used for application up to 12Gbps

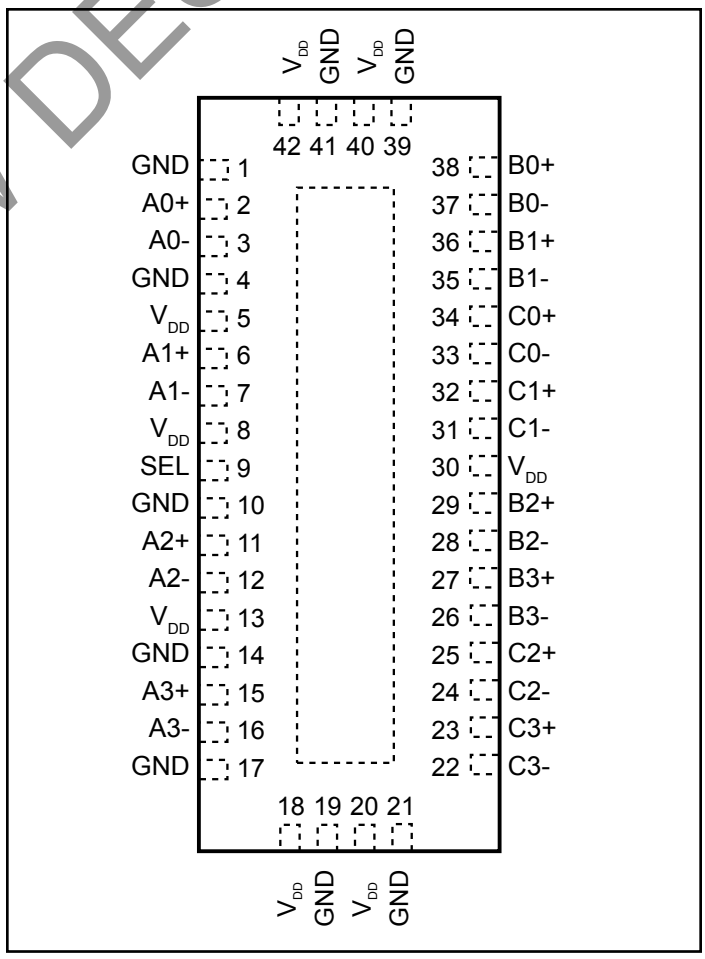
Application

Routing of PCI Express 3.0, DP1.2, USB3.0, SAS2.0, SATA3.0, XAUI, RXAUI signals with low signal attenuation.

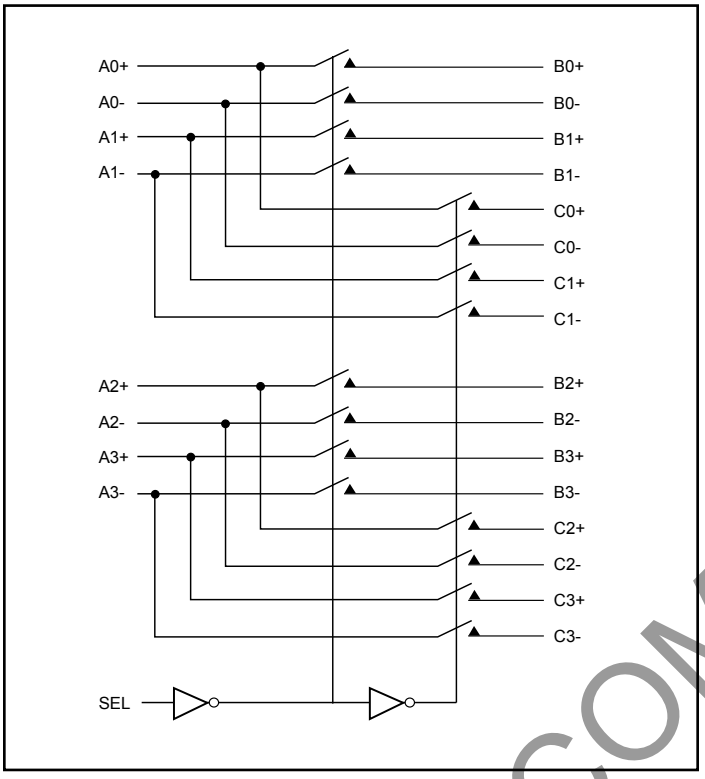
Pin Configuration - 40- Contact TQFN



Pin Configuration - 42- Contact TQFN



Block Diagram



Truth Table

Function	SEL
A_N to B_N	L
A_N to C_N	H

Pin Description

Pin #		Pin Name	I/O	Description
42-TQFN	40-TQFN			
2 3	1 2	A0+ A0–	I/O	Signal I/O, Channel 0, Port A
6 7	4 5	A1+ A1–	I/O	Signal I/O, Channel 1, Port A
11 12	9 10	A2+ A2–	I/O	Signal I/O, Channel 2, Port A
15 16	13 14	A3+ A3–	I/O	Signal I/O, Channel 3, Port A
38 37	36 35	B0+ B0–	I/O	Signal I/O, Channel 0, Port B
36 35	34 33	B1+ B1–	I/O	Signal I/O, Channel 1, Port B
29 28	26 25	B2+ B2–	I/O	Signal I/O, Channel 2, Port B
27 26	24 23	B3+ B3–	I/O	Signal I/O, Channel 3, Port B
34 33	32 31	C0+ C0–	I/O	Signal I/O, Channel 0, Port C
32 31	30 29	C1+ C1–	I/O	Signal I/O, Channel 1, Port C
25 24	22 21	C2+ C2–	I/O	Signal I/O, Channel 2, Port C
23 22	20 19	C3+ C3–	I/O	Signal I/O, Channel 3, Port C
9	7	SEL	I	Operation mode Select (when SEL=0: A→B, when SEL=1: A→C
5, 8, 13,18, 20, 30, 40, 42	3, 6, 11, 17, 28, 38	V_{DD}	Pwr	3.3V ±10% Positive Supply Voltage
1, 4, 10, 14, 17, 19, 21, 39, 41, Center Pad	8, 12, 15, 16, 18, 27, 37, 39, 40	GND	Pwr	Power ground

Maximum Ratings

(Above which useful life may be impaired. For user guidelines, not tested.)

Storage Temperature	–65°C to +150°C
Supply Voltage to Ground Potential	–0.5V to +4.6V
Channel DC Input Voltage	–0.5V to 1.5V
DC Output Current	120mA
Power Dissipation	0.5W
SEL DC Input Voltage	–0.5V to 4.6V

Note: Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Electrical Characteristics

Recommended Operating Conditions

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V_{DD}	3.3V Power Supply		3.0	3.3	3.6	V
I_{DD}	Total current from V_{DD} 3.3V supply	SEL = 0V or V_{DD}		0.15	1	mA
$V_{I/O}$-DIF	Differential Voltage (differential pins)				1.6	V_{ppd}
$V_{I/O-CM}$	Common Mode Voltage (differiential pins)		0		0.8	V
T_A	Operating temperature range		-40		85	°C

DC Electrical Characteristics for Switching over Operating Range

Parameters	Description	Test Conditions[1]	Min.	Typ.[1]	Max.	Units
V_{IH} - SEL	Input HIGH Voltage, SEL Input		2		3.6	V
V_{IL} - SEL	Input LOW Voltage, SEL Input		0		0.8	
V_{IK}	Clamp Diode Voltage	V_{DD} = Max., I_{IN} = –18mA		–0.7	–1.2	
IIH	Input HIGH Current, SEL	V_{DD} = Max., V_{IN} = V_{DD}			±5	µA
I_{IL}	Input LOW Current, SEL	V_{DD} = Max., V_{IN} = 0V			±5	
I_{IN} - SEL	Input Leakage Current, SEL Input	V_{IN} = V_{IH} - SEL Max or V_{IL} - SEL Min	–10		+10	µA
IIH	Input HIGH Current, A_X, B_X, C_X	V_{DD} = Max., V_{IN} = 1.5V	–10		+10	µA
I_{IL}	Input LOW Current, A_X, B_X, C_X	V_{DD} = Max., V_{IN} = 0V	–10		+10	
I_{OZH}	HighZ HIGH Current, B_X, C_X	V_{DD} = Max., V_{IN} = 1.5V	–10		+10	µA
I_{OZL}	HighZ LOW Current, B_X, C_X	V_{DD} = Max., V_{IN} = 0V	–10		+10	µA
$C_{I/O-ON}$	ON state I/O capacitance			1.5		pF
R_{ON}	ON state resistance	V_{DD} = 3.3V, IO = 8mA, V_{IN} = 0.8V		5		Ω

Note:

1. Typical values are at V_{DD} = 3.3V, T_A = 25°C ambient and maximum loading.

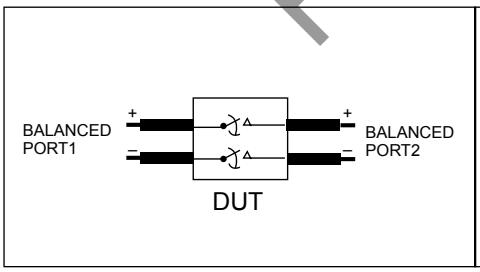
Switching Characteristics

Parameters	Description	Test Conditions	Min.	Typ.	Max.	Units
t_{PZH}, t_{PZL}	Line Enable Time - SEL to A_N, B_N, C_N		2	20	25	ns
t_{PHZ}, t_{PLZ}	Line Disable Time - SEL to A_N, B_N, C_N		0.5	5	25	
t_{b-b}	Bit-to-bit skew within the same differential pair			5	10	ps
t_{ch-ch}	Channel-to-channel skew				20	ps

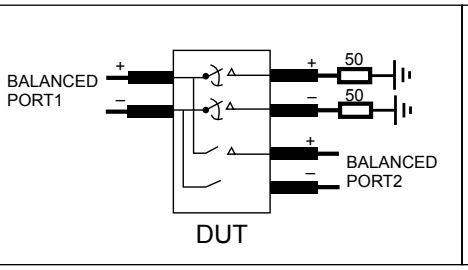
Dynamic Electrical Characteristics

Parameter	Description	Test Conditions	Min.	Typ.(1)	Max.	Units
DDIL	Differential Insertion Loss (V_{IN} = -10dBm, DC = 0V)	f= 50MHz - 1.25GHz f=1.25GHz - 2.5GHz f=2.5GHz - 4GHz f=5GHz		-0.8 -1.0 -1.3 -1.8	-1 -1.2 -1.6 -2.2	dB
$DDIL_{OFF}$	Differential Off Isolation	f= 50MHz - 1.25GHz f=1.25GHz - 2.5GHz f=2.5GHz - 4GHz f=5GHz	-26.3 -21.4 -17.6 -16	-32.9 -26.7 -22 -20		dB
DDRL	Differential Return Loss	f= 50MHz - 1.25GHz f=1.25GHz - 2.5GHz f=2.5GHz - 4GHz f=5GHz	-20 -18.4 -16.8 -9.6	-25 -23 -21 -12		dB
DDNEXT	Near End Crosstalk	f= 50MHz - 1.25GHz f=1.25GHz - 2.5GHz f=2.5GHz - 4GHz f=5GHz	-34.1 -30.5 -28.1 -27.2	-42.6 -38.1 -35.1 -34		dB
V_{IF}	Max Signal Frequency Range	Insertion loss 1.5dB, V_{IN}=0.623Vpp, DC=0V		4.0		GHz
		Insertion loss 1.5dB, V_{IN}=0.623Vpp, DC=0.9V		4.0		
		Insertion loss 3dB, V_{IN}=0.623Vpp, DC=0V		8.0		
		Insertion loss 3dB, V_{IN}=0.623Vpp, DC=0.9V		8.0		
BW	-3dB Bandwidth			8.2		GHz

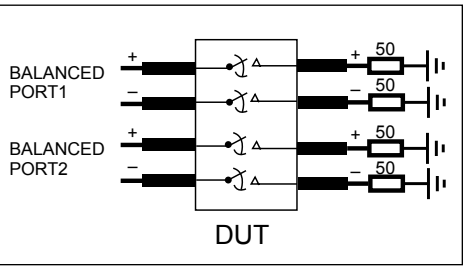
Notes:
1. Guaranteed by design. Typical values are at V_{DD} = 3.3V , T_A = 25°C ambient and maximum loading.



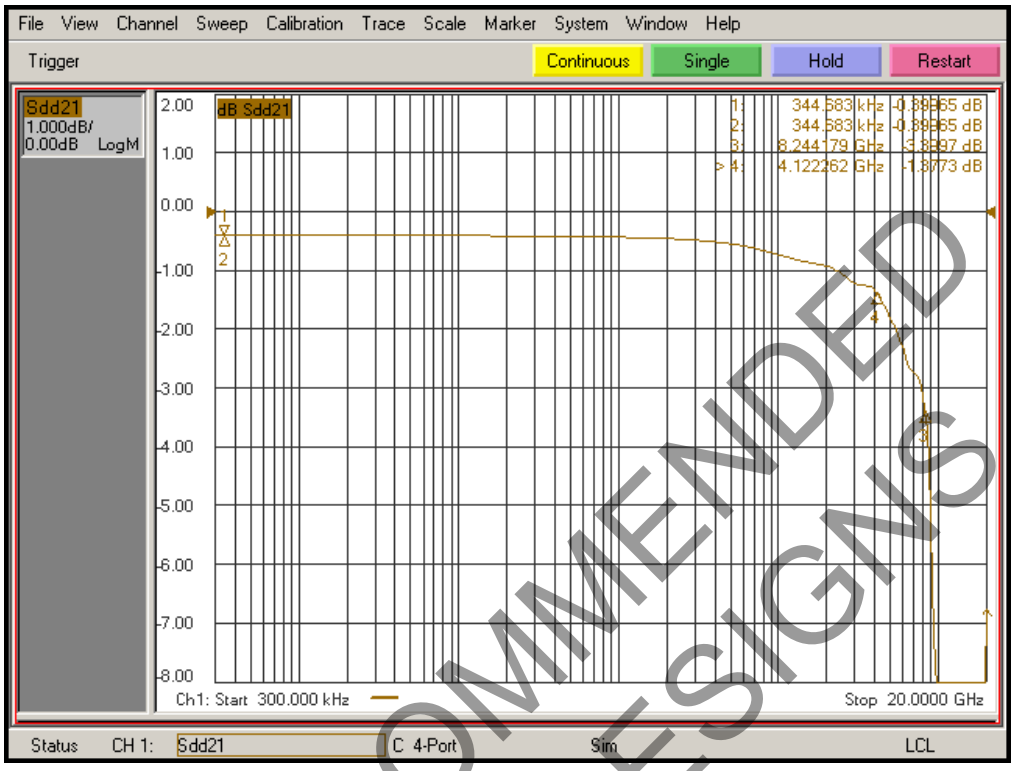
Diff. Insertion Loss and Return Test Circuit



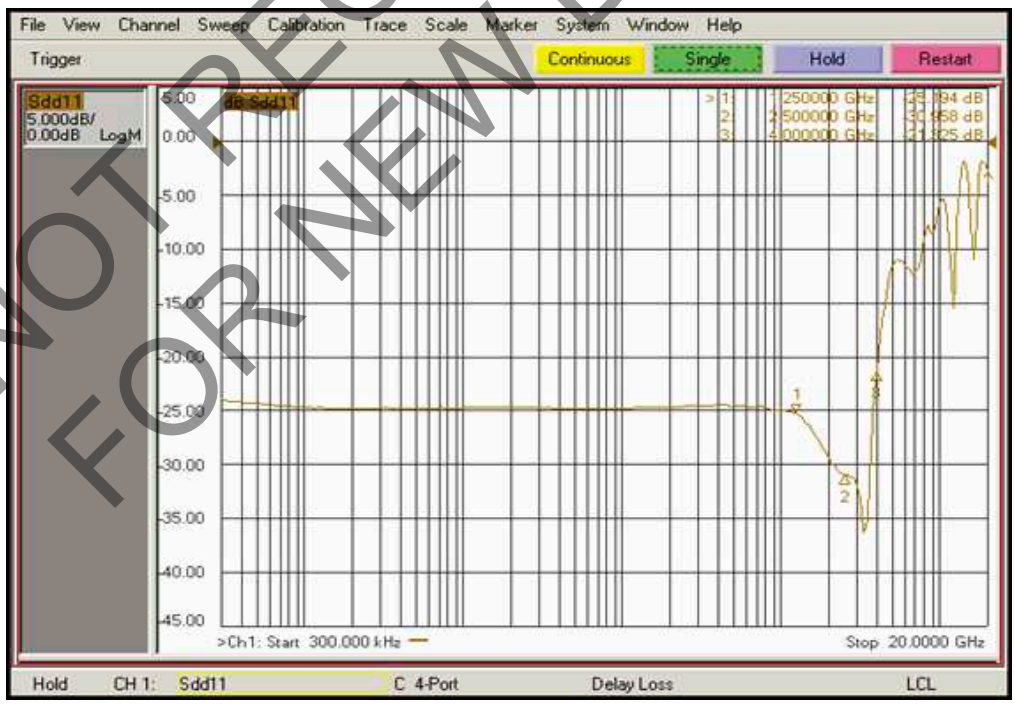
Diff. Off Isolation Test Circuit



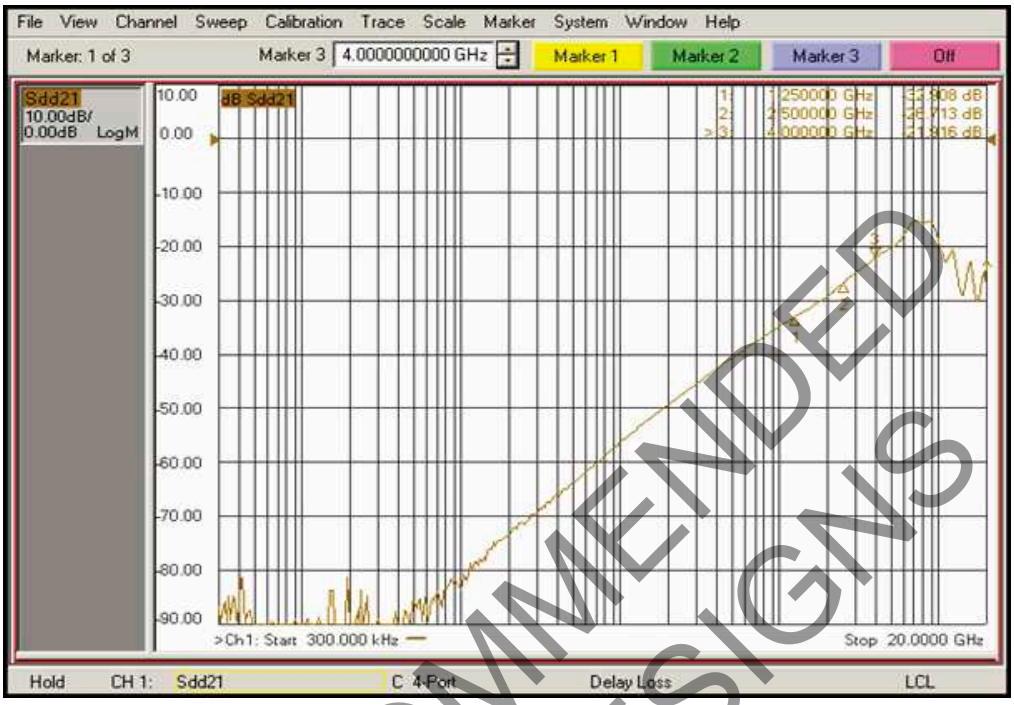
Diff. Near End Xtalk Test Circuit



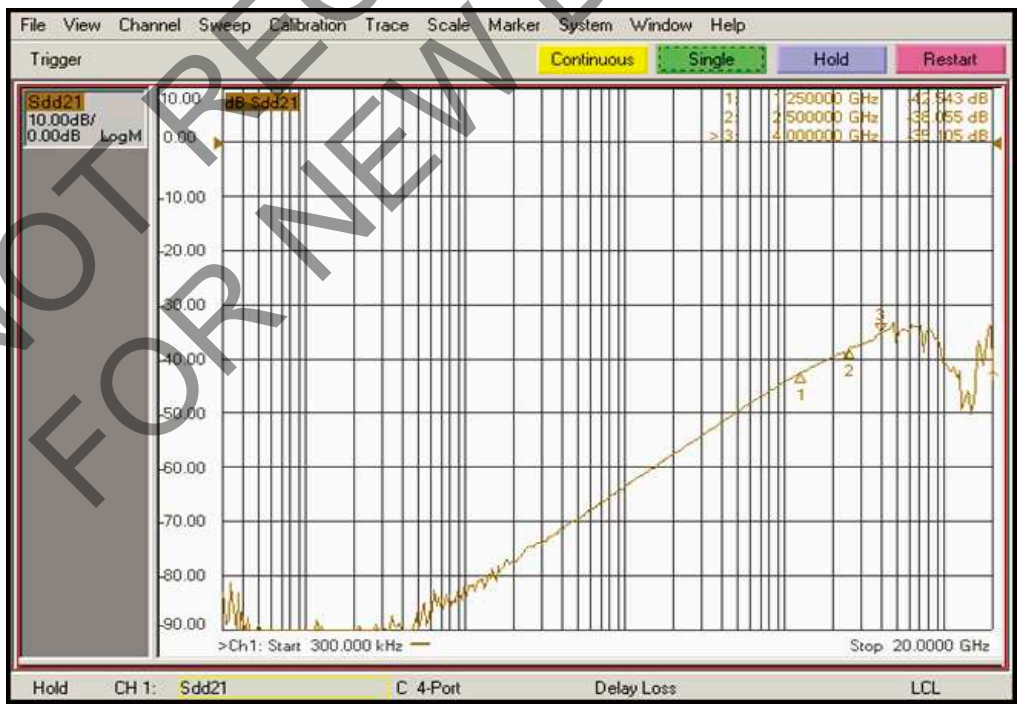
Differential Insertion Loss



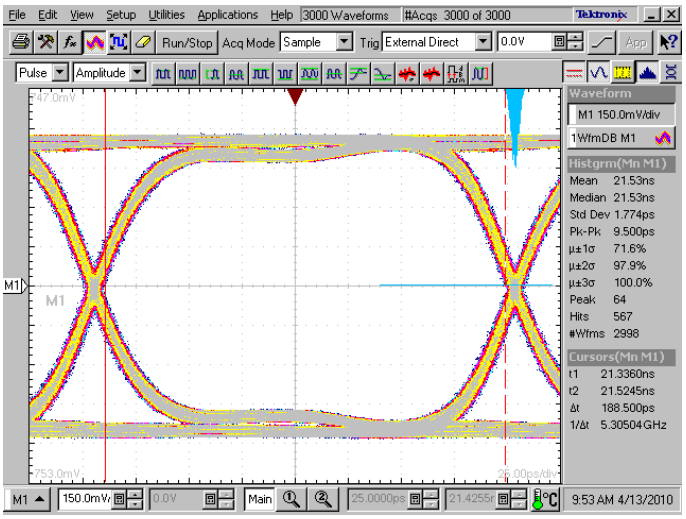
Differential Return Loss



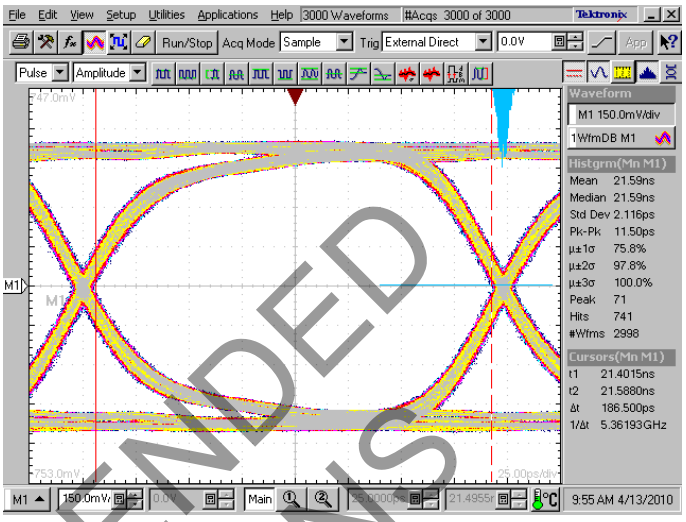
Differential Off Isolation



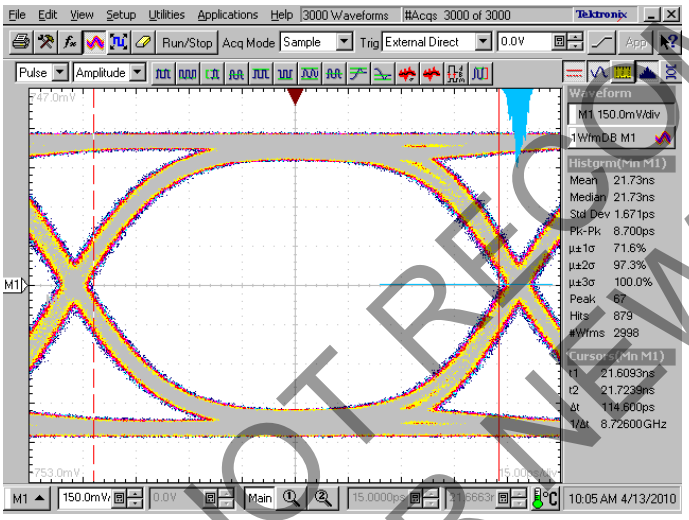
Differential Crosstalk



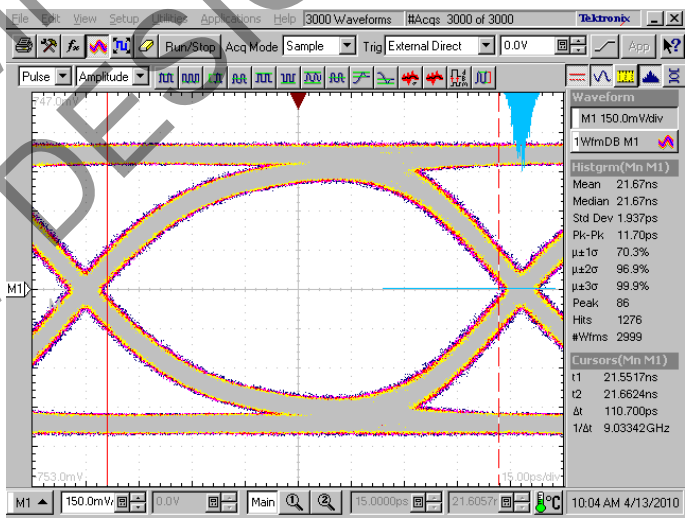
5.0 Gbps RX signal eye without PI3PCIE3412



5.0 Gbps RX signal eye with PI3PCIE3412

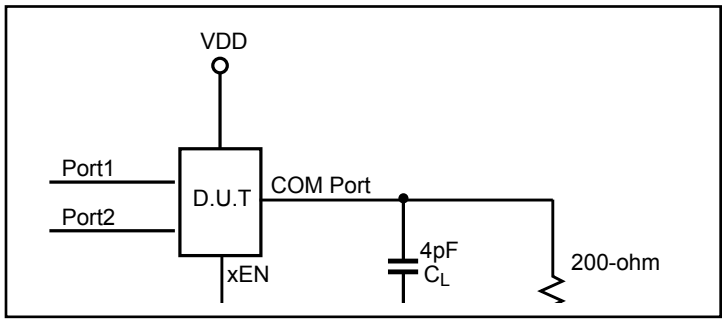


8.0 Gbps RX signal eye without PI3PCIE3412



8.0 Gbps RX signal eye with PI3PCIE3412

Test Circuit for Electrical Characteristics(1-5)



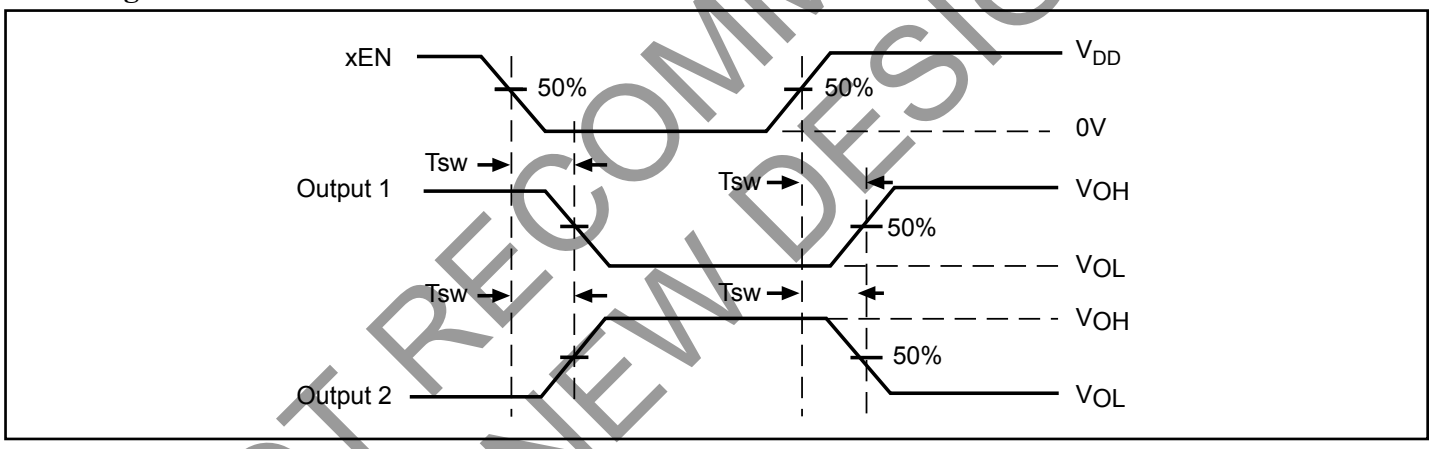
Switch Positions

Test	Switch
t_{PLZ}, t_{PZL}	3.0V
t_{PHZ}, t_{PZH}	GND
Prop Delay	Open

Notes:

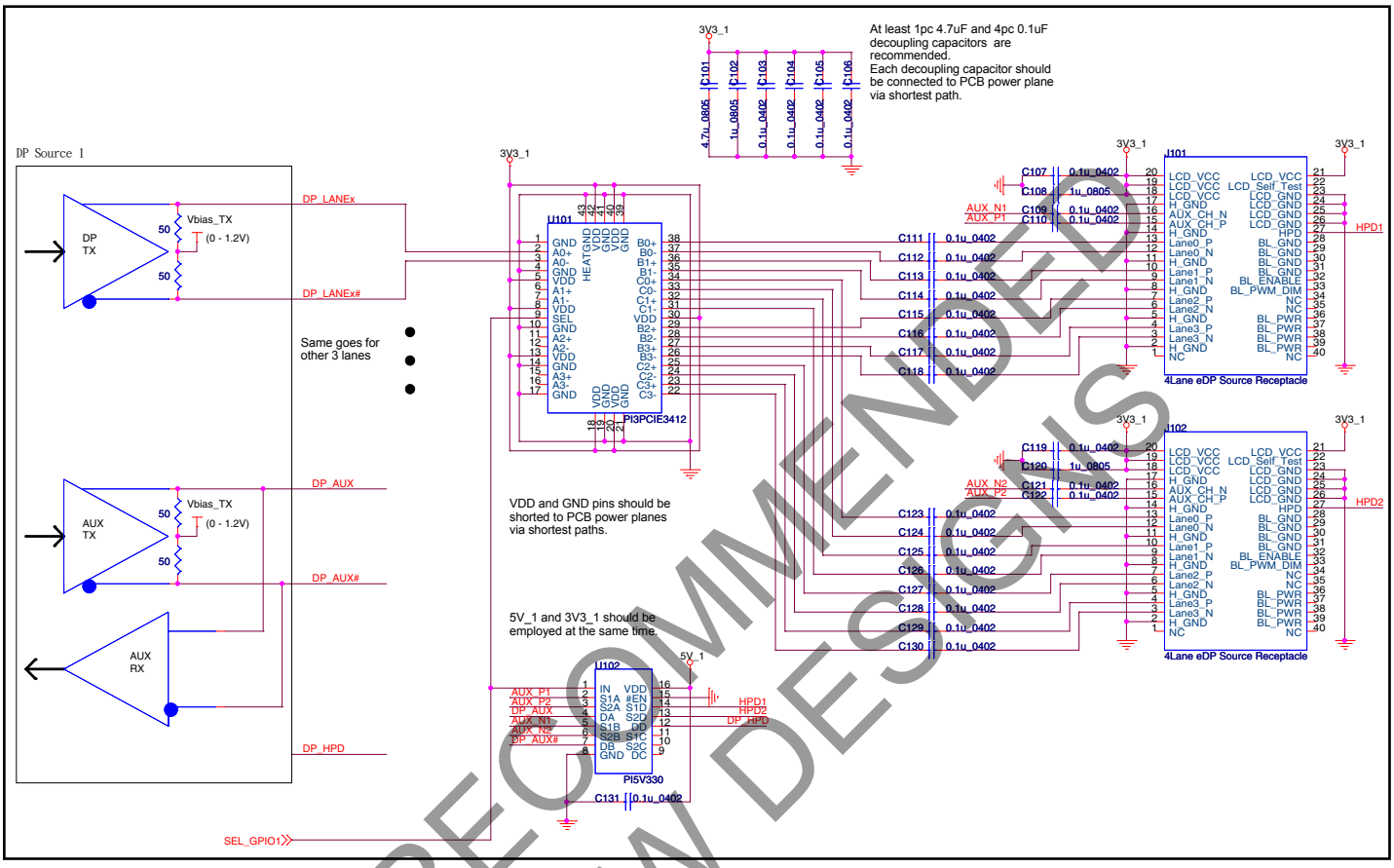
1. C_L = Load capacitance: includes jig and probe capacitance.
2. R_T = Termination resistance: should be equal to Z_{OUT} of the Pulse Generator
3. Output 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
   Output 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
4. All input impulses are supplied by generators having the following characteristics: PRR ≤ MHz, Z_O = 50Ω, t_R ≤ 2.5ns, t_F ≤ 2.5ns.
5. The outputs are measured one at a time with one transition per measurement.

Switching Waveforms

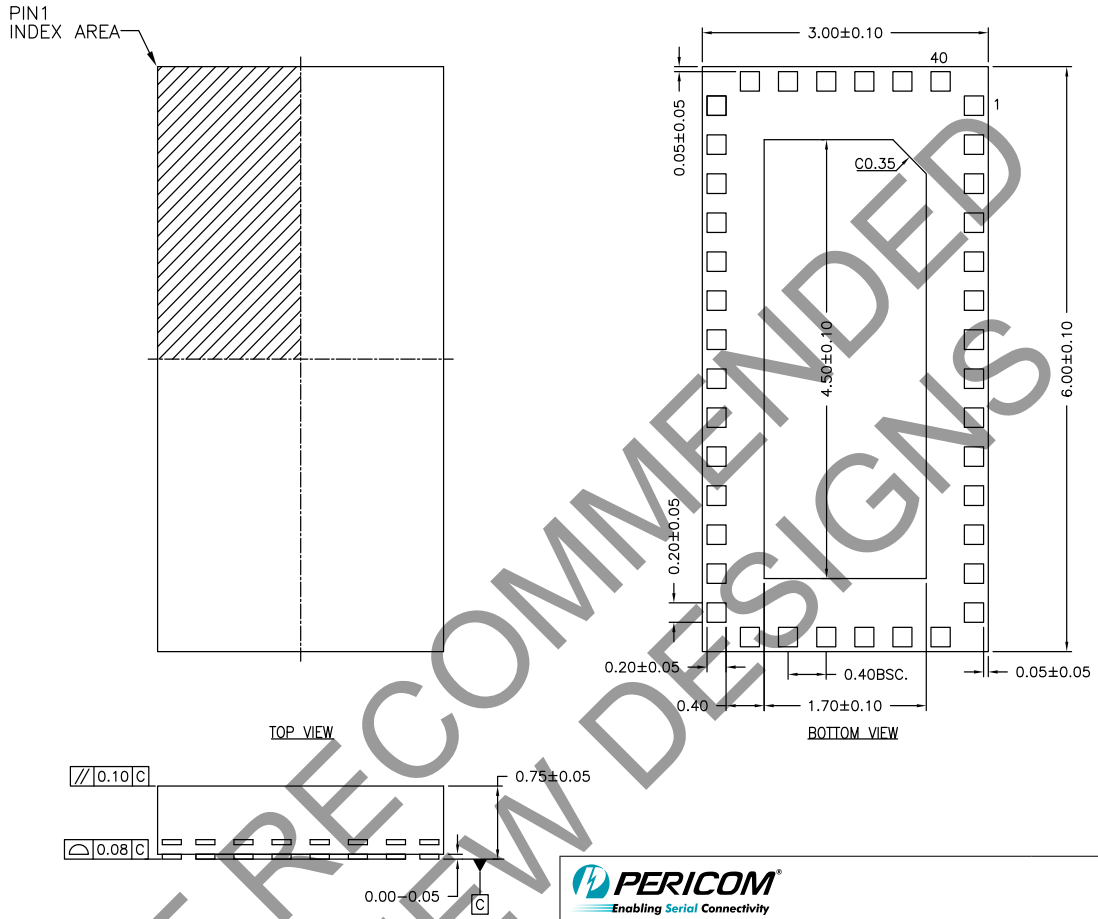


Voltage Waveforms Enable and Disable Times

DP1.2 Application



Packaging Information



Notes:
1. All dimensions are in mm. Angles in degrees.
2. Coplanarity applies to the exposed pad as well as the terminals.
3. Refer JEDEC MO-220

PERICOM Enabling Serial Connectivity

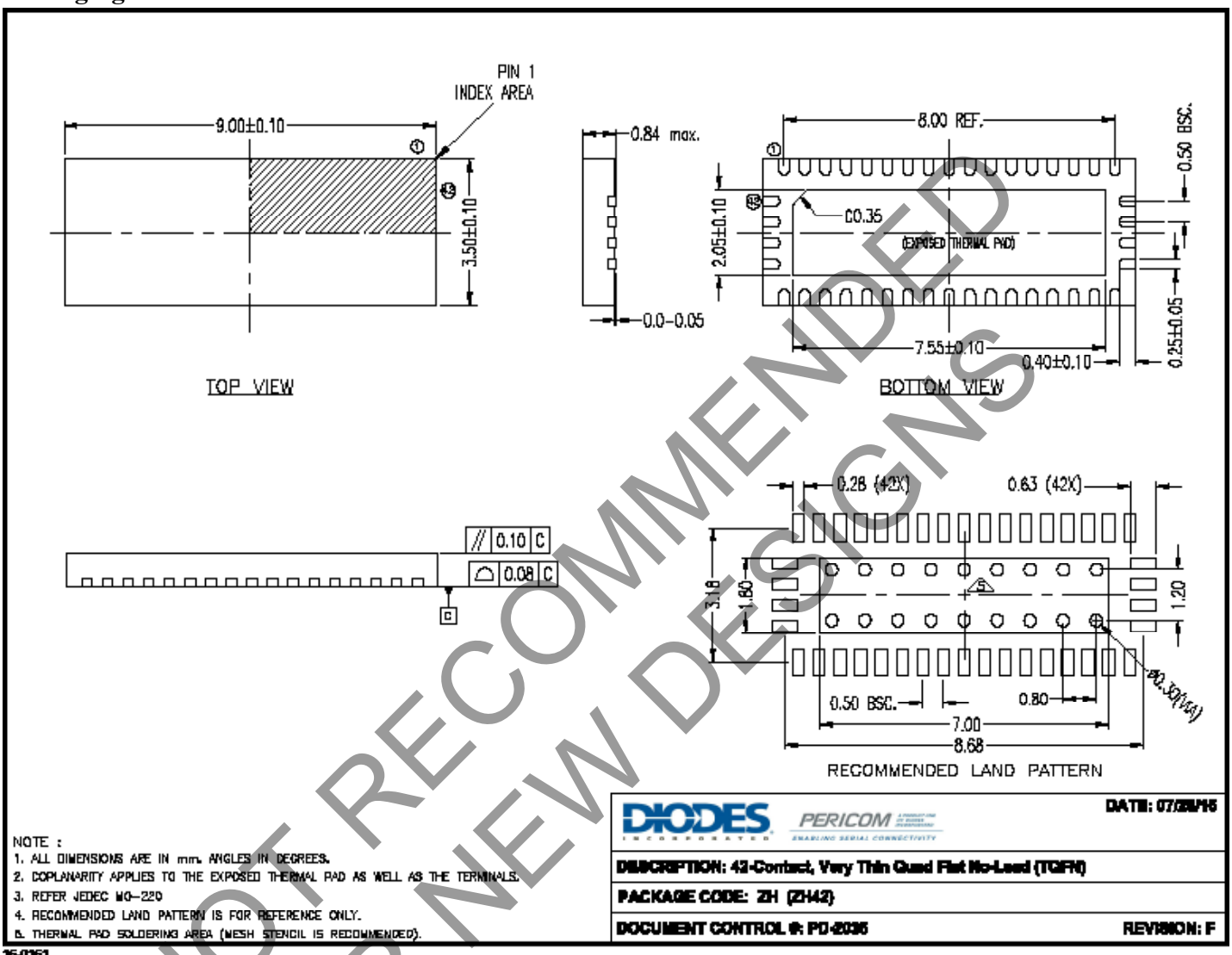
DATE: 07/11/13

DESCRIPTION: 40-contact, Thin Fine Pitch Quad Flat No-Lead, TQFN

PACKAGE CODE: ZL (ZL40)

DOCUMENT CONTROL #: PD-2165 **REVISION: --**

Packaging Information



Note: For latest package info, please check: http://www.pericom.com/support/packaging/packaging-mechanicals-and-thermal-characteristics/

Ordering Information

Ordering Code	Package Code	Package Description
PI3PCIE3412ZLE	ZL	40-contact, Thin Fine Pitch Quad Flat No-Lead (TQFN)
PI3PCIE3412ZLEX	ZL	40-contact, Thin Fine Pitch Quad Flat No-Lead (TQFN), Tape & Reel
PI3PCIE3412ZHE	ZH	42-contact, Very Thin Quad Flat No-Lead (TQFN)
PI3PCIE3412ZHEX	ZH	42-contact, Very Thin Quad Flat No-Lead (TQFN), Tape & Reel

Notes:
- Thermal characteristics can be found on the company web site at www.pericom.com/packaging/
- "E" denotes Pb-free and Green
- Adding an "X" at the end of the ordering code denotes tape and reel packaging

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